

# NCE N-Channel Enhancement Mode Power MOSFET

## Description

The NCE6020AK uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

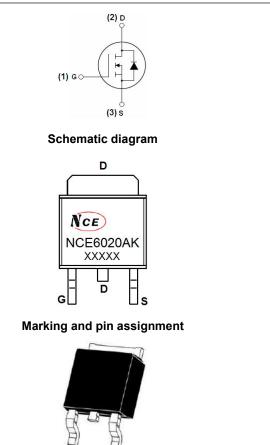
#### **General Features**

- V<sub>DS</sub> =60V,I<sub>D</sub> =20A
  R<sub>DS(ON)</sub> <35mΩ @ V<sub>GS</sub>=10V
  R<sub>DS(ON)</sub> <40mΩ @ V<sub>GS</sub>=4.5V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

## Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

100% UIS TESTED! 100% ΔVds TESTED!



TO-252-2L top view

#### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE6020AK	NCE6020AK	TO-252-2L	-	-	-

#### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	Vds	60	V	
Gate-Source Voltage	V <sub>GS</sub>	±20	V	
Drain Current-Continuous	Ι <sub>D</sub>	20	А	
Drain Current-Continuous(T <sub>C</sub> =100 ℃)	I <sub>D</sub> (100℃)	14	A	
Pulsed Drain Current <sup>(Note 1)</sup>	I <sub>DM</sub>	60	A	
Maximum Power Dissipation	PD	45	W	
Derating factor		0.3	W/℃	
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	72	mJ	
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C	

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	3.3	°C/W	
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## Electrical Characteristics (Tc=25°C unless otherwise noted)

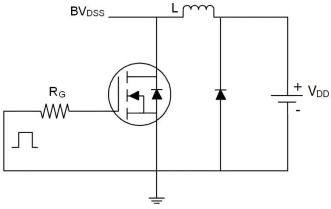
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	I		-			
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250µA	60	-	-	V
Zero Gate Voltage Drain Current	IDSS	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
On Characteristics (Note 3)			·			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=250\mu A$	1.2	1.6	2.5	V
Desir Deserve Or Otata Desistance	_	V <sub>GS</sub> =10V, I <sub>D</sub> =10A	-	24	35	mΩ
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	$V_{GS}$ =4.5V, $I_D$ =10A		30	40	
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =5V,I <sub>D</sub> =10A	11	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	Clss		-	973.2	-	PF
Output Capacitance	Coss	$V_{DS}$ =30V, $V_{GS}$ =0V,	-	61.2	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	F=1.0MHz	-	58.8	-	PF
Switching Characteristics (Note 4)			- I			
Turn-on Delay Time	t <sub>d(on)</sub>		-	7	-	nS
Turn-on Rise Time	tr	V <sub>DD</sub> =30V,R <sub>L</sub> =3Ω V <sub>GS</sub> =10V,R <sub>G</sub> =3Ω	-	20	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	16	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	23	-	nS
Total Gate Charge	Qg	N/ 001/1 404	-	25		nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}=30V,I_{D}=10A,$	-	4.5		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	6.5		nC
Drain-Source Diode Characteristics	I		-			
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	20	A
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF =10A	-	29	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	49	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negl	igible (turi	n-on is do	minated b	y LS+LD)

## Notes:

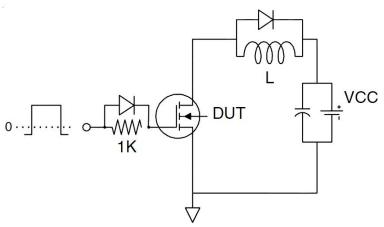
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.
- **3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.
- 4. Guaranteed by design, not subject to production
- **5.** EAS condition:Tj=25°C, $V_{DD}$ =30V, $V_G$ =10V,L=0.5mH,Rg=25 $\Omega$



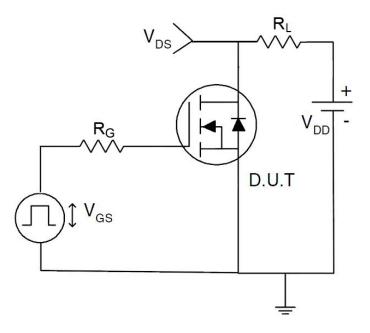
## Test Circuit 1) E<sub>AS</sub> test Circuit



2) Gate charge test Circuit



3) Switch Time Test Circuit





100

20

30

25℃

0.6

0.8

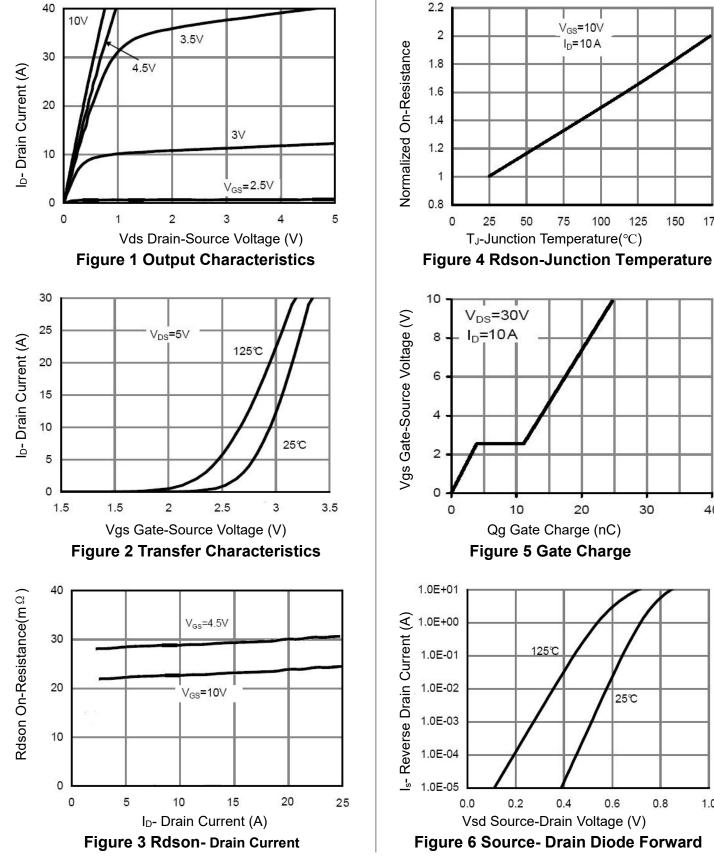
125

150

175

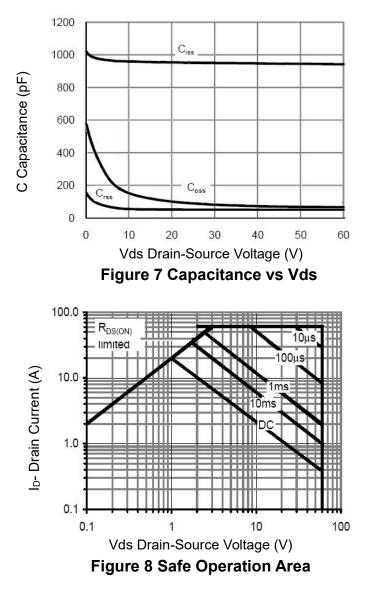
40





1.0





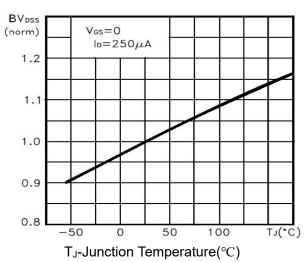


Figure 9 BV<sub>DSS</sub> vs Junction Temperature

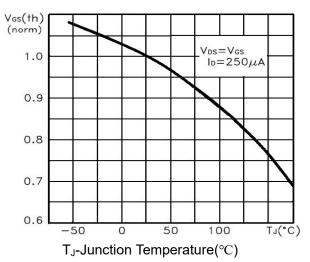


Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

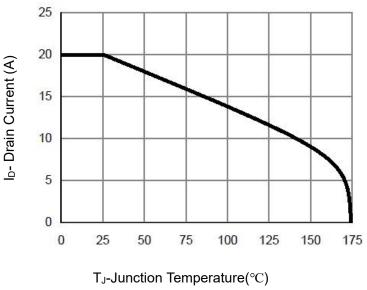
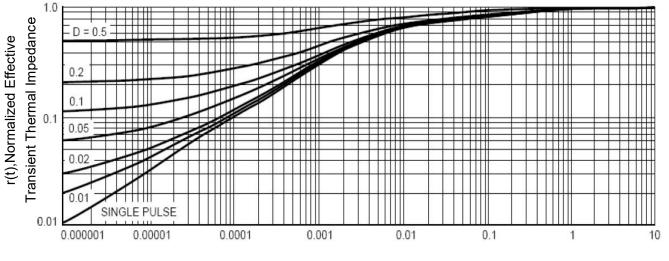


Figure 11 Current De-rating



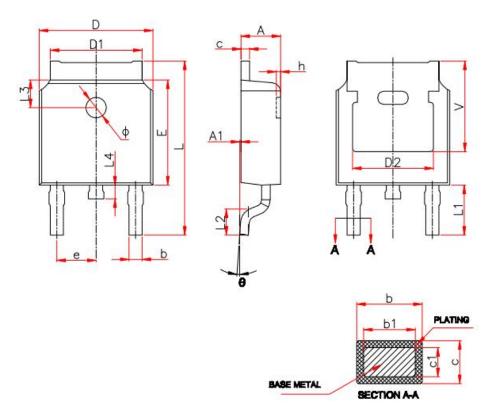
http://www.ncepower.com



Square Wave Pluse Duration (sec) Figure 12 Normalized Maximum Transient Thermal Impedance



# TO-252-2L Package Information



Symbol	Millimeters			
Symbol	Min.	Max.		
A	2.20	2.40		
A1	0.00	0.13		
b	0.66	0.86		
b1	0.73	0.79		
С	0.46	0.58		
c1	0.50	0.52		
D	6.50	6.70		
D1	5.10	5.46		
D2	4.83 REF.			
E	6.00	6.20		
е	2.19	2.39		
L	9.80 10.4			
L1	2.90	REF.		
L2	1.40	1.70		
L3	1.60 REF.			
L4	0.60	1.00		
Φ	1.10	1.30		
θ	0°	8°		
h	0.00	0.30		
V	5.35	REF.		



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